

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A piezoelectric device having a structure in which a piezoelectric resonator element is bonded to electrodes provided on a package base, comprising:

silicone-based conductive adhesives;

mounting electrodes provided on the package base, to which a driving voltage is carried via conduction paths, and on which the piezoelectric resonator element is mounted, the mounting electrodes defining surfaces; and

conductive anchor members which are disposed on the surfaces of the mounting electrodes and which are formed of a material having high adhesion to the surfaces of the mounting electrodes, the piezoelectric resonator element being bonded to the conductive anchor members with the silicone-based conductive adhesives provided therebetween,

wherein the conductive anchor members include a conductive adhesive formed of a rigid resin.

2. (Canceled)

3. (Previously Presented) The piezoelectric device according to Claim 1, the conductive anchor members including at least one of an epoxy-based and a polyimide-based conductive adhesive.

4.-7. (Canceled)

8. (Previously Presented) The piezoelectric device according to Claim 1, wherein the surface of the mounting electrode is a gold (Au) electrode film.

9. (Canceled)